


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G473CEU3 STM32G473CEU3TR	7FMI*469XXX	A	998Z	17-02-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	103.42	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.55	48	flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	7FMI*469XXX				6000000.0	1000047.5
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.180	mg	Supplier	die	Silicon (Si)	7440-21-3		5.592	mg	904854	54071
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.028	mg	4531	271
				Supplier	metallization	Copper (Cu)	7440-50-8		0.249	mg	40291	2408
				Supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	162	10
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.081	mg	13107	783
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	485	29
				Supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	324	19
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.063	mg	10194	609
				Supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	26052	1557
				Glue epoxy (EN4900GC-SD)	M-011 Other inorganic materials	2.067	mg	Supplier	Organic Compounds	Acrylic resin	Trade Secret	
Supplier	Organic Compounds	Polybutadiene derivative	Trade Secret						0.041	mg	20000	400
Supplier	Organic Compounds	Butadiene copolymer	Trade Secret						0.031	mg	15000	300
Supplier	Organic Compounds	Acrylate	Trade Secret						0.112	mg	54000	1079
Supplier	Organic Compounds	Epoxy resin	Trade Secret						0.062	mg	30000	600
Supplier	Organic Compounds	Peroxide	Trade Secret						0.017	mg	8000	160
Supplier	Organic Compounds	Additive	Trade Secret						0.037	mg	18000	360
Supplier	Metals	Silver	7440-22-4						1.623	mg	785000	15691
Encapsulation (EME-G770)	M-011 Other inorganic materials	32.496	mg	Supplier	Organic Compounds	Epoxy Resin A	Trade Secret		0.682	mg	21000	6599
				Supplier	Organic Compounds	Epoxy Resin B	Trade Secret		0.682	mg	21000	6599
				Supplier	Organic Compounds	Phenol Resin A	Trade Secret		0.682	mg	21000	6599
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		25.362	mg	780450	245240
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		3.747	mg	115320	36237
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.202	mg	6230	1958
				Supplier	Metallic compounds	Metal Hydroxide	Trade Secret		0.455	mg	14000	4399
				Supplier	Organic Compounds	Phenol Resin B	Trade Secret		0.682	mg	21000	6599
Wire (Au 3N)	Bonding Wire	0.568	mg	Supplier	Metals	Gold	7440-57-5		0.568	mg	1000000	5488
Plating Anode (Pure Tin)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin	7440-31-5		1.078	mg	1000000	10428
Leadframe (C7025+Ag)	Copper & its alloys	61.032	mg	Supplier	Metals	Copper	7440-50-8		55.975	mg	917140	541257
				Supplier	Metals	Nickel	7440-02-0		1.373	mg	22500	13279
				Supplier	Metals	Silicon	7440-21-3		0.159	mg	2600	1534
				Supplier	Metals	Magnesium	7439-95-4		0.070	mg	1150	679
				Supplier	Metals	Silver	7440-22-4		3.455	mg	56610	33409